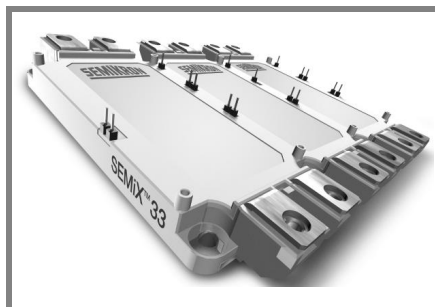


# SEMiX 353GD126HDc



**SEMiX® 33c**

## Trench IGBT Modules

### SEMiX 353GD126HDc

Preliminary Data

#### Features

- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$  with positive temperature coefficient
- High short circuit capability

#### Typical Applications

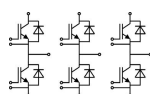
- AC inverter drives
- UPS
- Electronic Welding

#### Remarks

- Case temperatur limited to  $T_C=125^\circ\text{C}$  max.

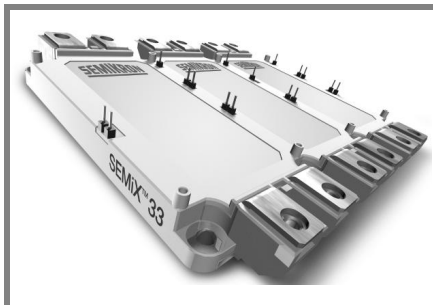
| Absolute Maximum Ratings |  | $T_{case} = 25^\circ\text{C}$ , unless otherwise specified |                  |   |
|--------------------------|--|--|------------------|---|
| Symbol                   | Conditions   | Values   | Units            |   |
| <b>IGBT</b>              |  |  |                  |   |
| $V_{CES}$                | $T_j = 25^\circ\text{C}$   | 1200   | V                |   |
| $I_C$                    | $T_j = 150^\circ\text{C}$  | $T_c = 25^\circ\text{C}$                                   | 365              | A |
|                          |  | $T_c = 80^\circ\text{C}$                                   | 255              | A |
| $I_{CRM}$                | $I_{CRM} = 2 \times I_{Cnom}$  | 450  | A                |   |
| $V_{GES}$                |  | $\pm 20$   | V                |   |
| $t_{psc}$                | $V_{CC} = 600\text{ V}; V_{GE} \leq 20\text{ V}; T_j = 125^\circ\text{C}$<br>$V_{CES} < 1200\text{ V}$ | 10   | $\mu\text{s}$    |   |
| <b>Inverse Diode</b>     |  |  |                  |   |
| $I_F$                    | $T_j = 150^\circ\text{C}$  | $T_c = 25^\circ\text{C}$                                   | 330              | A |
|                          |  | $T_c = 80^\circ\text{C}$                                   | 225              | A |
| $I_{FRM}$                | $I_{FRM} = 2 \times I_{Fnom}$  | 450  | A                |   |
| $I_{FSM}$                | $t_p = 10\text{ ms}; \text{sin.}$  | $T_j = 25^\circ\text{C}$                                   | 1700             | A |
| <b>Module</b>            |  |  |                  |   |
| $I_{t(RMS)}$             |  | 600  | A                |   |
| $T_{vj}$                 |  | - 40 ... + 150   | $^\circ\text{C}$ |   |
| $T_{stg}$                |  | - 40 ... + 125   | $^\circ\text{C}$ |   |
| $V_{isol}$               | AC, 1 min.   | 4000   | V                |   |

| Characteristics |   | $T_{case} = 25^\circ\text{C}$ , unless otherwise specified |      |      |                  |
|-----------------|---|--|------|------|------------------|
| Symbol          | Conditions                                      | min.   | typ. | max. | Units            |
| <b>IGBT</b>     |   |  |      |      |                  |
| $V_{GE(th)}$    | $V_{GE} = V_{CE}, I_C = 9\text{ mA}$            | 5  | 5,8  | 6,5  | V                |
| $I_{CES}$       | $V_{GE} = 0\text{ V}, V_{CE} = V_{CES}$         |  |      | 0,3  | mA               |
| $V_{CE0}$       |   | $T_j = 25^\circ\text{C}$                                   | 1    | 1,2  | V                |
|                 |   | $T_j = 125^\circ\text{C}$                                  | 0,9  | 1,1  | V                |
| $r_{CE}$        | $V_{GE} = 15\text{ V}$                          | $T_j = 25^\circ\text{C}$                                   | 3,1  | 4,2  | $\text{m}\Omega$ |
|                 |   | $T_j = 125^\circ\text{C}$                                  | 4,9  | 6    | $\text{m}\Omega$ |
| $V_{CE(sat)}$   | $I_{Cnom} = 225\text{ A}, V_{GE} = 15\text{ V}$ | $T_j = 25^\circ\text{C}_{chiplev.}$                        | 1,7  | 2,1  | V                |
|                 |   | $T_j = 125^\circ\text{C}_{chiplev.}$                       | 2    | 2,4  | V                |
| $C_{ies}$       | $V_{CE} = 25, V_{GE} = 0\text{ V}$              | $f = 1\text{ MHz}$   | 16   |      | nF               |
| $C_{oes}$       |   |  | 0,84 |      | nF               |
| $C_{res}$       |   |  | 0,73 |      | nF               |
| $Q_G$           | $V_{GE} = -8 \dots +15\text{V}$                 |  | 1800 |      | nC               |
| $t_{d(on)}$     | $R_{Gon} = 2\ \Omega$                           | $V_{CC} = 600\text{V}$<br>$I_{Cnom} = 225\text{A}$         | 265  |      | ns               |
| $t_r$           |   |  | 55   |      | ns               |
| $E_{on}$        | $R_{Goff} = 2\ \Omega$                          | $T_j = 125^\circ\text{C}$                                  | 26,5 |      | mJ               |
| $t_{d(off)}$    |   |  | 585  |      | ns               |
| $t_f$           |   |  | 120  |      | ns               |
| $E_{off}$       |   |  | 32,5 |      | mJ               |
| $R_{th(j-c)}$   | per IGBT  |  |      | 0,1  | K/W              |



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### SEMiX 353GD126HDc

#### Preliminary Data

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- $V_{CE(sat)}$  with positive temperature coefficient
- High short circuit capability

#### Typical Applications

- AC inverter drives
- UPS
- Electronic Welding

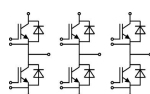
#### Remarks

- Case temperatur limited to  $T_C=125^\circ\text{C}$  max.

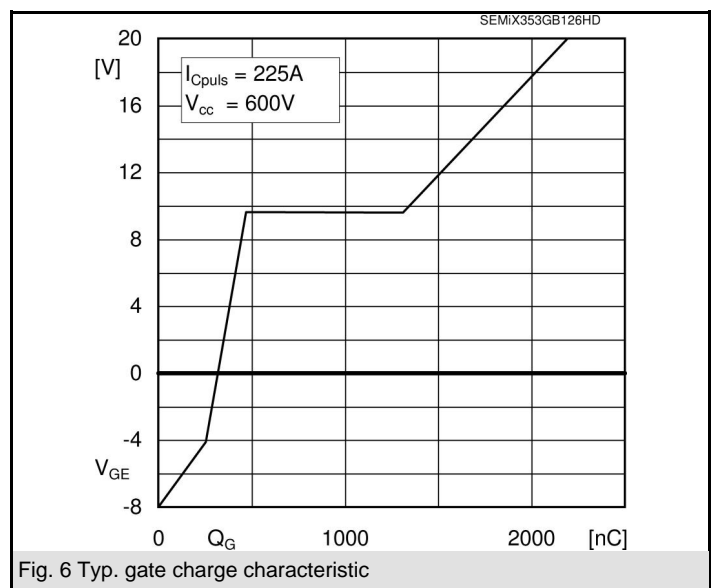
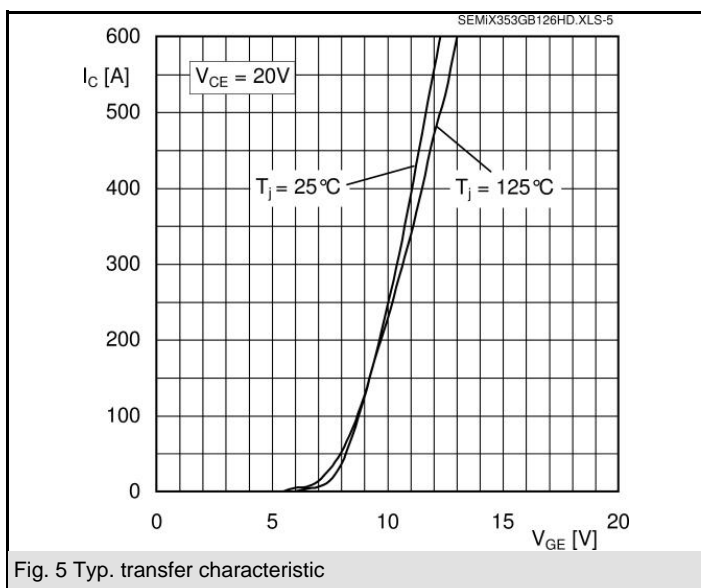
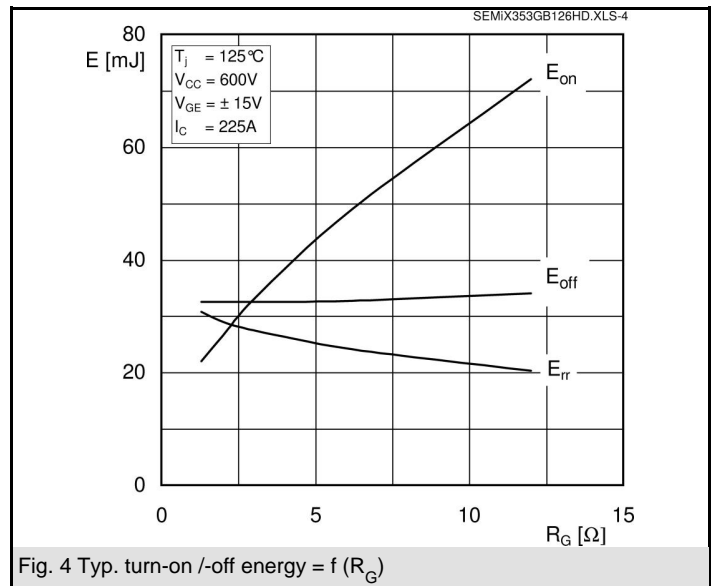
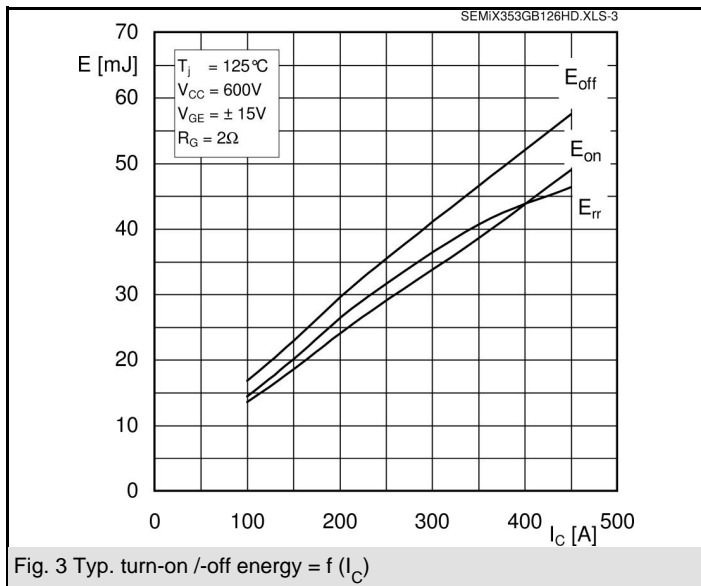
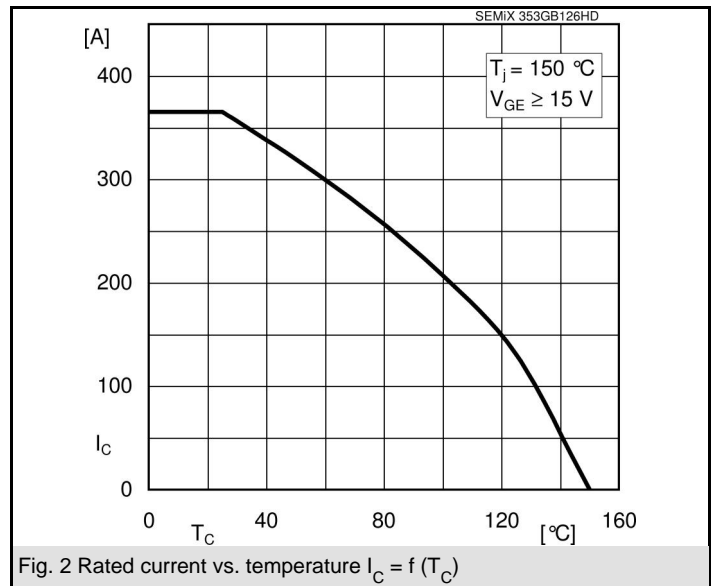
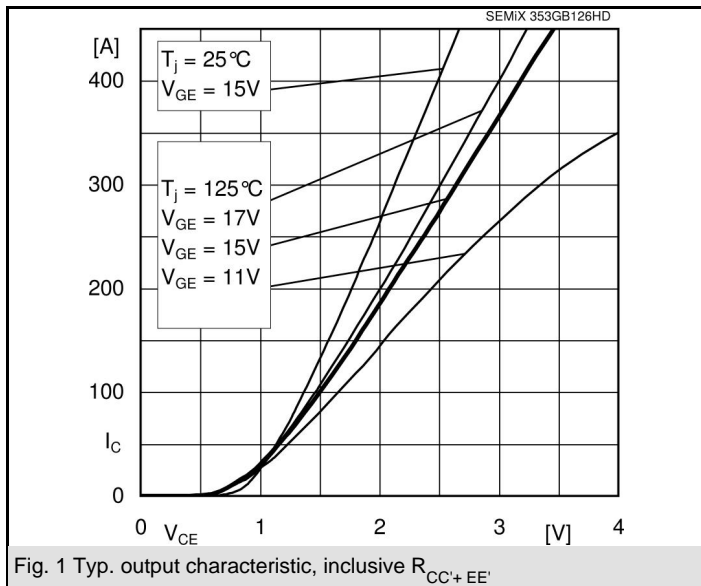
| Characteristics           |  | min.                           | typ.     | max. | Units |
|---------------------------|--|--------------------------------|----------|------|-------|
| <b>Inverse Diode</b>      |  |                                |          |      |       |
| $V_F = V_{EC}$            | $I_{Fnom} = 225 \text{ A}; V_{GE} = 0 \text{ V}$                           |                                | 1,6      | 1,8  | V     |
|                           | $T_j = 25^\circ\text{C}_{chiplev.}$  |                                |          |      |       |
|                           | $T_j = 125^\circ\text{C}_{chiplev.}$                                       |                                | 1,6      | 1,8  | V     |
| $V_{F0}$                  |  |                                | 1        | 1,1  | V     |
|                           | $T_j = 25^\circ\text{C}$   |                                |          |      |       |
|                           | $T_j = 125^\circ\text{C}$  |                                | 0,8      | 0,9  | V     |
| $r_F$                     |  |                                | 2,7      | 3,1  | mΩ    |
|                           | $T_j = 25^\circ\text{C}$   |                                |          |      |       |
|                           | $T_j = 125^\circ\text{C}$  |                                | 3,6      | 4    | mΩ    |
| $I_{RRM}$                 | $I_{Fnom} = 225 \text{ A}$   |                                | 330      |      | A     |
| $Q_{rr}$                  | $di/dt = 5600 \text{ A}/\mu\text{s}$                                       |                                | 69       |      | μC    |
| $E_{rr}$                  | $V_{GE} = -15 \text{ V}; V_{CC} = 600 \text{ V}$                           |                                | 29       |      | mJ    |
| $R_{th(j-c)D}$            | per diode  |                                |          | 0,17 | K/W   |
| <b>Module</b>             |  |                                |          |      |       |
| $L_{CE}$                  |  |                                | 20       |      | nH    |
| $R_{CC'+EE'}$             | res., terminal-chip  | $T_{case} = 25^\circ\text{C}$  | 0,7      |      | mΩ    |
|                           |  | $T_{case} = 125^\circ\text{C}$ | 1        |      | mΩ    |
| $R_{th(c-s)}$             | per module   |                                | 0,014    |      | K/W   |
| $M_s$                     | to heat sink (M5)  |                                | 3        | 5    | Nm    |
| $M_t$                     | to terminals (M6)  |                                | 2,5      | 5    | Nm    |
| w                         |  |                                |          | 900  | g     |
| <b>Temperature sensor</b> |  |                                |          |      |       |
| $R_{100}$                 | $T_c = 100^\circ\text{C}$ ( $R_{25} = 5 \text{ k}\Omega$ )                 |                                | 0,493±5% |      | kΩ    |
| $B_{100/125}$             | $R(T) = R_{100} \exp[B_{100/125} (1/T - 1/T_{100})]$ ;<br>$T[\text{K}]; B$ |                                | 3550±2%  |      | K     |

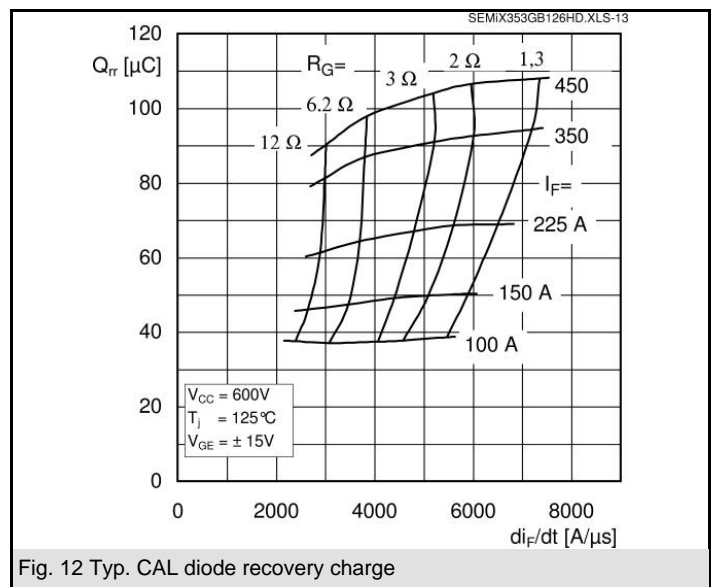
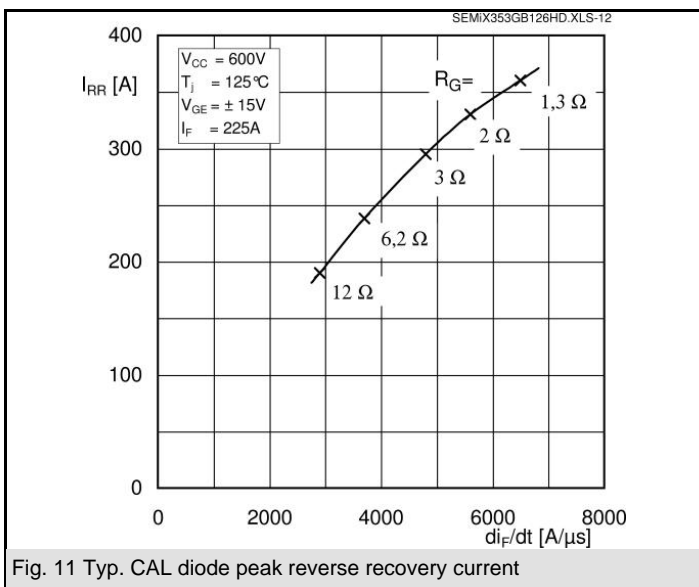
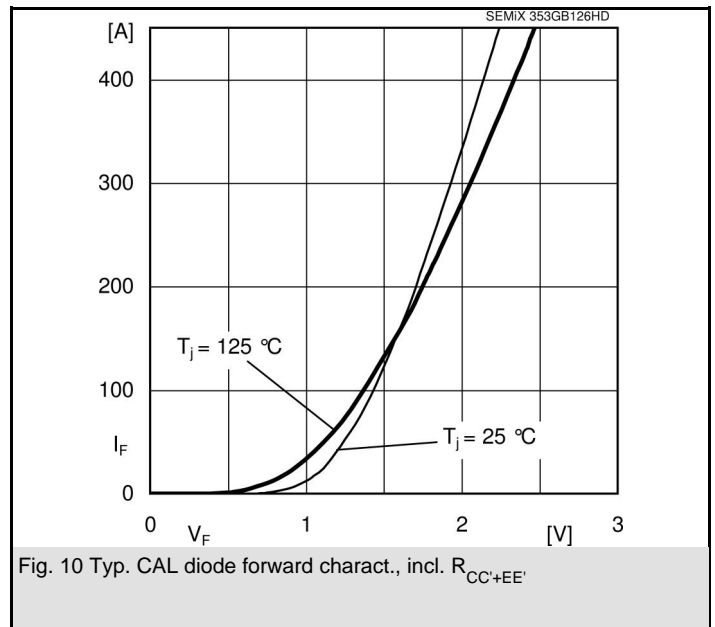
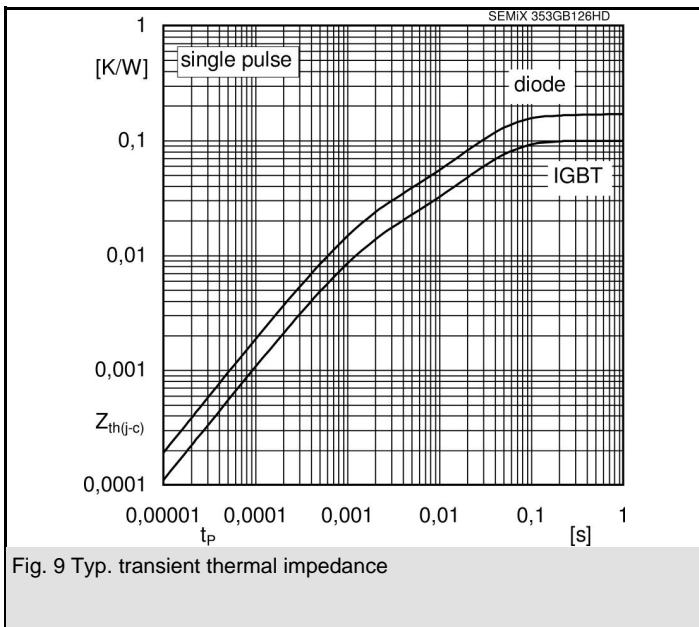
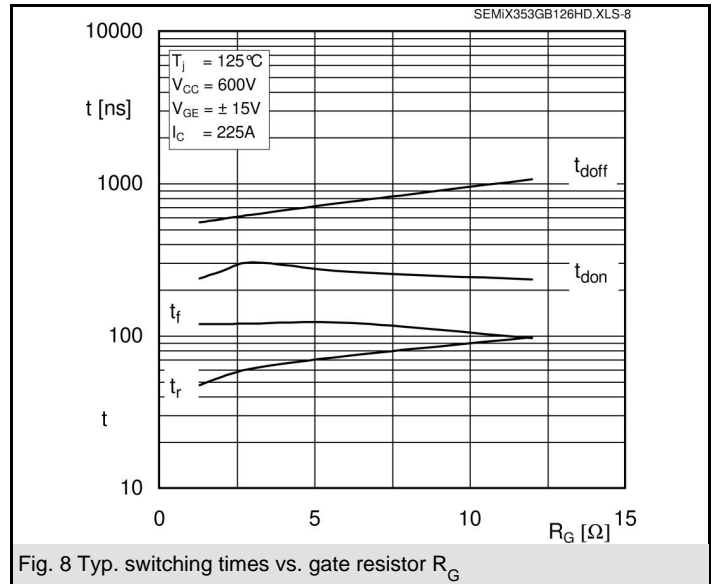
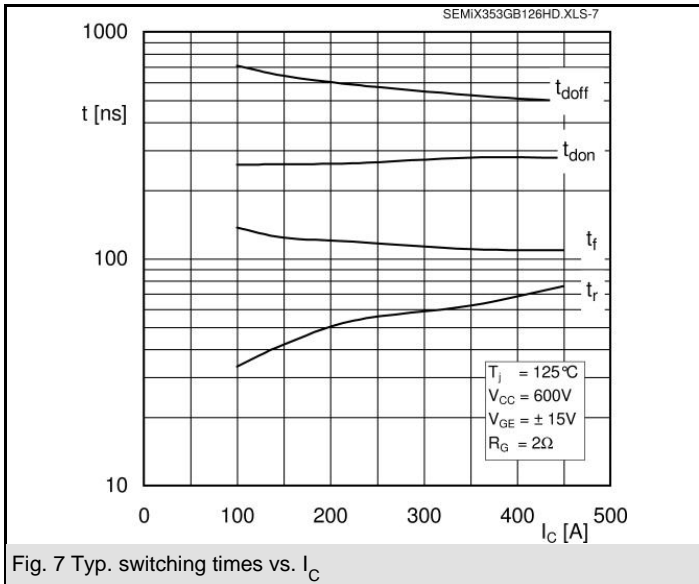
This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.

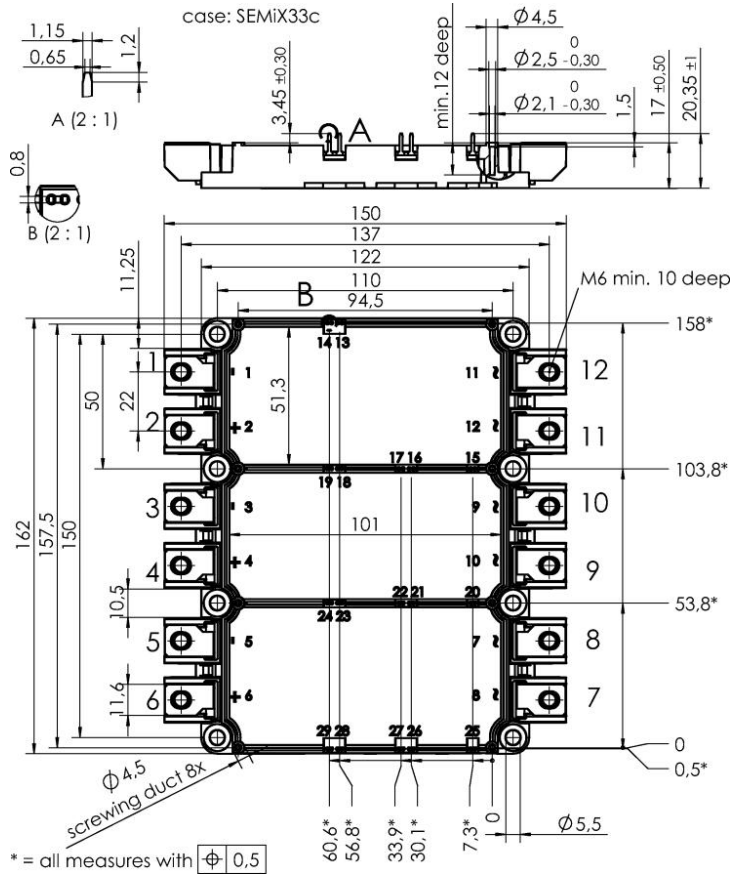


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# SEMiX 353GD126HDc



Case SEMiX 33c

